



Material Content Data Sheet



Sales Product Name				BSC035N04LS G		Issued		4. October 2018	
MA#				MA001831310					
Package				PG-TDSON-8-39		Weight*		112.59 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.840	1.63	1.63	16344	16344	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129		
	non noble metal	iron	7439-89-6	0.048	0.04		430		
	non noble metal	copper	7440-50-8	48.352	42.97	43.02	429461	430020	
	non noble metal	copper	7440-50-8	0.045	0.04	0.04	396	396	
wire	non noble metal	copper	7440-50-8	0.045	0.04	0.04	396	396	
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		734		
	plastics	epoxy resin	-	6.531	5.80		58004		
	inorganic material	silicondioxide	60676-86-0	34.719	30.84	36.71	308373	367111	
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13501	13501	
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1407	1407	
solder	non noble metal	tin	7440-31-5	0.038	0.03		337		
	noble metal	silver	7440-22-4	0.047	0.04		421		
	non noble metal	lead	7439-92-1	1.813	1.61	1.68	16099	16857	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2639	2643	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		150		
	noble metal	silver	7440-22-4	0.150	0.13		1332		
	non noble metal	copper	7440-50-8	16.910	15.02	15.17	150194	151721	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com